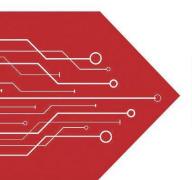
# MSKSEMI















**ESD** 

TVS

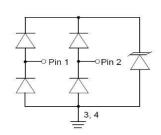
**TSS** 

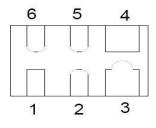
MOV

**GDT** 

**PLED** 

Broduct data sheet





SLP1610P4

#### **Features**

- ◆ 150 Watts peak pulse power (tp = 8/20µs)
- ◆ Transient protection for high speed data lines to
- ♦ IEC 61000-4-2 (ESD) ±15kV (air), ±8kV (contact) IEC 61000-4-4 (EFT) 40A (5/50ns)
- ♦ Working voltages : 5V
- ◆ Protects One Power or I/O Port
- ◆ Low operating and clamping voltages
- ◆ Solid-state silicon avalanche technology

## **Applications**

- Notebooks, Desktops, Servers and Video Graphics Cards
- ◆ USB Power & Data Line Protection
- ♦ Monitors and Flat Panel Displays
- ♦ I<sup>2</sup>C Bus Protection
- ◆ Portable Instrumentation
- ♦ Set Top Box

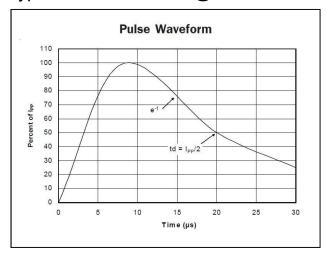
## Electrical Characteristics@ Ta=25°C unless otherwise

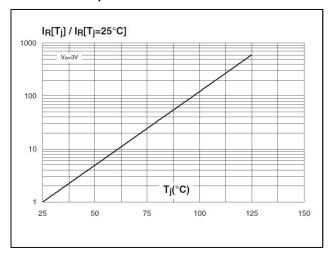
	VRWM@IR		VBR@ImA	Vc@1A	Vc	@IPP	CJ
P/N	V	μΑ	V	V	V	Α	pF
		MAX	MIN	MAX	MAX		TYP
RCLAMP0522P-MS	5	1	5.8	11.8	15	3	0.5

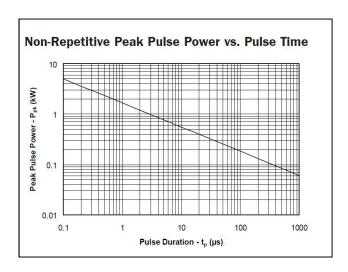
## Maximum Rating @ Ta=25℃ unless otherwise specified

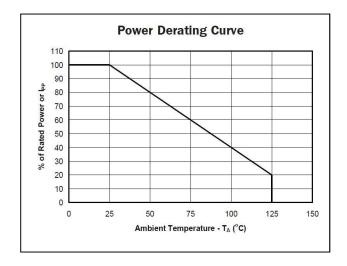
Symbol	Parameter	Ratings	Units
Ррк	Peak Pulse Power (tp = 8/20μs)	150	Watts
TL	Lead Soldering Temperature	260(10sec.)	$^{\circ}$
TJ	Operating Temperature	-55 to +125	$^{\circ}$
Тѕтс	Storage Temperature	-55 to +150	$^{\circ}$

## Typical Characteristics@ Ta=25°C unless otherwise specified



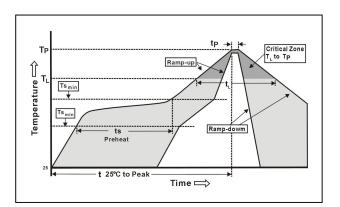






## **Soldering Parameters**

Reflow Condition		Fb – Free assembly	
	-Temperature Min (T <sub>s(Min)</sub> )	150°C	
Pre Heat	- Temperature Max (T <sub>s(Max)</sub> )	200°C	
	-Time (Min to max) (t <sub>s</sub> )	60 – 180 secs	
Average ramp up rate (Liquidus) Temp (T <sub>1</sub> ) to peak		3°C/second Max	
T <sub>S (Max)</sub> to T <sub>L</sub> - Ramp-up Rate		3°C/second Max	
Poflow	-Temperature (T <sub>L</sub> ) (Liquidus)	217°C	
Reflow	-Temperature (t <sub>L</sub> )	60 – 150 seconds	
Peak Temp	perature (T <sub>p</sub> )	250+0/-5 °C	
Time within 5°C of actual peak Temperature (t <sub>p</sub> )		20 – 40 seconds	
Ramp-dov	vm Rate	6°C/second Max	
Time 25°C	to peak Temperature (T <sub>P</sub> )	8 minutes Max.	
Do not exc	eed	260°C	



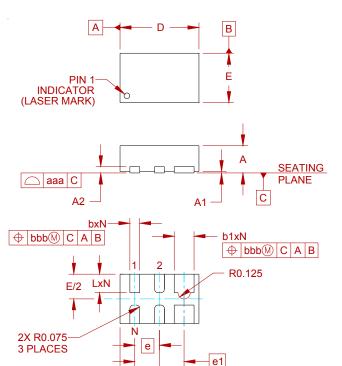








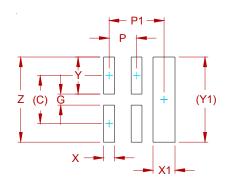




DIMENSIONS						
	11	<b>ICHE</b>	S	MILLIMETERS		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	.020	.023	.026	0.50	0.58	0.65
A1	0.00	.001	.002	0.00	0.03	0.05
A2		(.005)			(0.13)	
b	.006	.008	.010	0.15	0.20	0.25
b1	.014	.016	.018	0.35	0.40	0.45
D	.059	.063	.067	1.50	1.60	1.70
E	.035	.039	.043	0.90	1.00	1.10
е	.020 BSC			0.	50 BS	C
e1	.039 BSC			1.00 BSC		
L	.012	.015	.017	0.30	0.38	0.43
N	4				4	
aaa	.003			0.08		
bbb	.004				0.10	

NOTES: 1. CONTROLLING DIMENSIONS ARE IN MILLIMETERS (ANGLES IN DEGREES).

### **Suggested Pad Layout**



D/2

DIMENSIONS			
DIM	INCHES	MILLIMETERS	
С	(.034)	(0.87)	
G	.007	0.19	
Р	.020	0.50	
P1	.039	1.00	
X	.008	0.20	
X1	.016	0.40	
Υ	.027	0.68	
Y1	(.061)	(1.55)	
Ζ	.061	1.55	

#### NOTES:

- 1. CONTROLLING DIMENSIONS ARE IN MILLIMETERS (ANGLES IN DEGREES).
- 2. THIS LAND PATTERN IS FOR REFERENCE PURPOSES ONLY. CONSULT YOUR MANUFACTURING GROUP TO ENSURE YOUR COMPANY'S MANUFACTURING GUIDELINES ARE MET.

#### **REEL SPECIFICATION**

P/N	PKG	QTY
RCLAMP0522P-MS	SLP1610P4	3000



Semiconductor

#### Compiance

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